

Abstract

The disclosure provides a bonding alignment system, bonding device, and bonding method. The bonding alignment system comprises: a first target, on which a first target point is set to calibrate a first position of a wafer; a transparent second target, located between the first target and an image capture device, wherein a second target point is set on the transparent second target to calibrate a second position of a component to be bonded; the image capture device, for capturing a first image with the first target point and a second image with the second target point via an optical compensation assembly, to indicate an alignment deviation between the first position and the second position; and the optical compensation assembly, located between the second target and the image capture device, and comprising a plurality of optical path regions

(FIG. 1)